



Palladium Gen3

The banking industry reference for Palladium plating configuration

Linxens Palladium Gen3 is the industry reference for Palladium plating with Gold flash configuration beneath the Palladium layer for improved product cost-efficiency. Palladium Gen3 maintains the highest yield for wire bonding and optimal corrosion performance.

Key Features

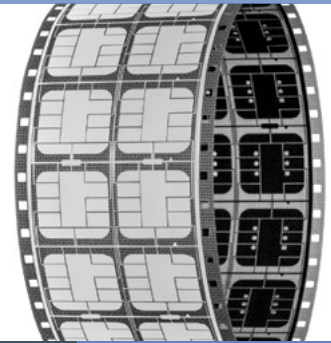
- Standard corrosion resistance
- Featured for payment cards
- Contact solution
- Palladium layer
- Contact solution

Typical Product Designs

Part Number	Modules	Cavity	Chip Dimension
9X12121	8	No	3.6 x 3.65 mm
9X16001	8	✓	3.6 x 3.6 mm
9X16004	8	No	4.8 x 4.8 mm
9X23206	8	✓	3.8 x 6.6 mm
9X23207	8	No	5.6 x ≤ 8 mm
9X13902	6	No	3.2 x 3 mm
9X13705	6	No	3 x 3 mm



MICROCONNECTORS



Overview

Material

- Film base: Standard epoxy glass
- Adhesive: High temperature modified Epoxy MCHT
- Copper: ED29 μ

Thickness

- Total: 159 \pm 20 μ m
- Plating Thickness
 - Contact side:
 - Ni: 2.0 (-0.6 + 1) μ m
 - Au: Gold flash
 - Pd: 0.15 \pm 0.05 μ m
 - Back side:
 - Ni: 5.0 (-2 +3) μ m
 - Au: 0.3 (-0.1 +0.2) μ m

Temperature Resistance

- 3 minutes at 260°C
- 21 hours at 160°C

Plating Performance

Corrosion resistance: High
Chemical resistance: High

Compliance Labels

- ISO 10373
- ISO 7810

Application Area

- Financial services

Options

- Micro-etched / Fully-etched
- Colored Tape: Red, blue, orange